



Features

Low On-Resistance ESD Protected Gate

Mechanical Data

Method 208 (e3)

Case: SC59

12V N-CHANNEL ENHANCEMENT MODE MOSFET

Totally Lead-Free & Fully RoHS compliant (Notes 1 & 2) Halogen and Antimony Free. "Green" Device (Note 3) Qualified to AEC-Q101 Standards for High Reliability

Case Material - Molded Plastic. UL Flammability Rating 94V-0

Terminals: Finish - Matte Tin Solderable per MIL-STD-202,

Moisture Sensitivity: Level 1 per J-STD-020

Terminal Connections: See Diagram Weight: 0.014 grams (approximate)

Product Summary

V _{(BR)DSS}	R _{DS(ON)} MAX	Ι _D T _A = +25°C
	10mΩ @ V _{GS} = 4.5V	9.3A
	12mΩ @ V _{GS} = 2.5V	8.5A
12V	14mΩ @ V _{GS} = 1.8V	7.9A
	18mΩ @ V _{GS} = 1.5V	6.9A
	41mΩ @ V _{GS} = 1.2V	4.6A

Description

This new generation MOSFET has been designed to minimize the onstate resistance ($R_{DS(ON)}$) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

Applications

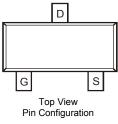
- Load Switch
- DC-DC Converters
- Power Management Functions

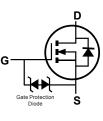
SC59





Top View





Equivalent Circuit

Ordering Information (Note 4)

Part Number	Case	Packaging
DMN1019USN-7	SC59	3,000/Tape & Reel
DMN1019USN-13	SC59	10,000/Tape & Reel

1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.

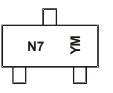
2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.

3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information

Notes:



N7 = Product Type Marking Code YM = Date Code Marking Y = Year ex: A = 2013 M = Month ex: 9 = September

Date Code Key												
Year	2013		2014	2015		2016	2017		2018	2019		2020
Code	A		В	С		D	E		F	G		Н
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D



Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Units			
Drain-Source Voltage	V _{DSS}	12	V			
Gate-Source Voltage	V _{GSS}	±8	V			
Continuous Drain Current (Note 6))/ 4 5)/	Steady State	T _A = +25°C T _A = +70°C	Ι _D	9.3 7.4	А	
Continuous Drain Current (Note 6) V_{GS} = 4.5V	t<10s	T _A = +25°C T _A = +70°C	ID	11 8.8	A	
Pulsed Drain Current (10µs pulse, duty cycle = 1%)	I _{DM}	70	А			
Maximum Body Diode Forward Current (Note 6)	Is	2	А			

Thermal Characteristics

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Characteristic	_	Symbol	Value	Units	
Tatal Dawar Dissinction (Nata 5)	T _A = +25°C	D	0.68	W	
Total Power Dissipation (Note 5)	T _A = +70°C	PD	0.4		
Thermal Registence, Junction to Ambient (Note 5)	Steady state	Devi	160	°C/W	
Thermal Resistance, Junction to Ambient (Note 5)	t<10s	R _{0JA}	115	°C/W	
Total Power Dissipation (Note 6)	T _A = +25°C	D	1.2	W	
Total Power Dissipation (Note 0)	T _A = +70°C	PD	0.83	vv	
Thermal Resistance, Junction to Ambient (Note 6)	Steady state	Р	96	°C/W	
mermar Resistance, Junction to Ambient (Note 0)	t<10s	$R_{\theta JA}$	68	°C/W	
Thermal Resistance, Junction to Case (Note 6)		R _{θJC}	18	°C/W	
Operating and Storage Temperature Range		T _{J.} T _{STG}	-55 to +150	°C	

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 7)			- 71-			L	
Drain-Source Breakdown Voltage	BV _{DSS}	12		_	V	V _{GS} = 0V, I _D = 250µA	
Zero Gate Voltage Drain Current	I _{DSS}			1	μA	V _{DS} =12V, V _{GS} = 0V	
Gate-Body Leakage	I _{GSS}		_	±2	μA	$V_{GS} = \pm 8V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 7)					-		
Gate Threshold Voltage	V _{GS(th)}	0.35	0.53	0.8	V	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	
		—	7	10		V _{GS} = 4.5V, I _D = 9.7A	
		—	8	12		V _{GS} = 2.5V, I _D = 9A	
Static Drain-Source On-Resistance	R _{DS(ON)}	—	10	14	mΩ	V _{GS} = 1.8V, I _D = 8.1A	
			14	18		V _{GS} = 1.5V, I _D = 4.5A	
			28	41		V _{GS} = 1.2V, I _D = 2.4A	
Forward Transfer Admittance	IY _{fs} I		28	_	S	V _{DS} = 4V, I _D = 9.7A	
Diode Forward Voltage	V _{SD}		0.8	1.2	V	V _{GS} = 0V, I _S = 10A	
DYNAMIC CHARACTERISTICS (Note 8)	· · · · ·				•	+	
Input Capacitance	C _{iss}	—	2426	-	pF		
Output Capacitance	C _{oss}	—	396	-	pF	[−] V _{DS} = 10V, V _{GS} = 0V, f = 1MHz	
Reverse Transfer Capacitance	C _{rss}	_	375	—	pF		
Gate Resistance	Rg	—	1.1	-	Ω	V_{DS} = 0V, V_{GS} = 0V, f = 1MHz	
Total Gate Charge (V _{GS} = 8V)	Qg	_	50.6	_			
Total Gate Charge (V _{GS} = 4.5V)	Qq		27.3	_	-0		
Gate-Source Charge	Q _{gs}		3.4	_	nC	$V_{DS} = 4V$, $I_D = 10A$	
Gate-Drain Charge	Q _{qd}		5.2	_			
Turn-On Delay Time	t _{D(ON)}	—	7.6	_	ns		
Turn-Off Delay Time	t _{D(OFF)}	_	22.2	_	ns	V _{DD} = 4V, V _{GEN} = 5V, I _D = 10A,	
Turn-On Rise Time	tr	_	57.6	_	ns	$R_G = 1\Omega, R_L = 0.4\Omega$	
Turn-Off Fall Time	t _f		16.8	_	ns		

5. Device mounted on FR-4 PCB with minimum recommended pad layout, single sided. The power dissipation P_D is based on t<10s R_{BJA} . 6. Device mounted on 1" x 1" FR-4 PCB with high coverage 2 oz. Copper, single sided. The power dissipation P_D is based on t<10s R_{BJA} . 7. Short duration pulse test used to minimize self-heating effect. 8. Guaranteed by design. Not subject to production testing.

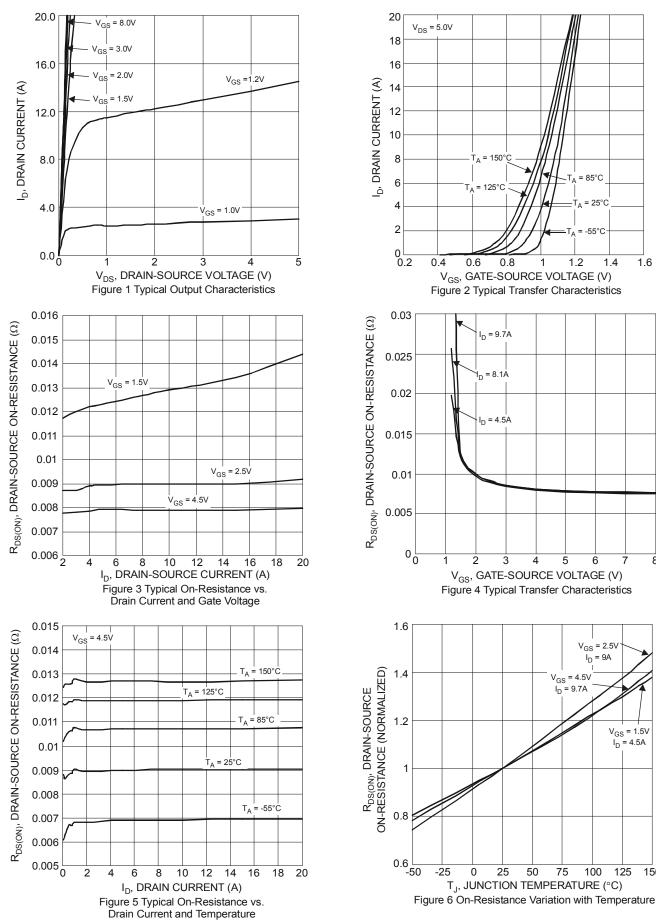
Notes:



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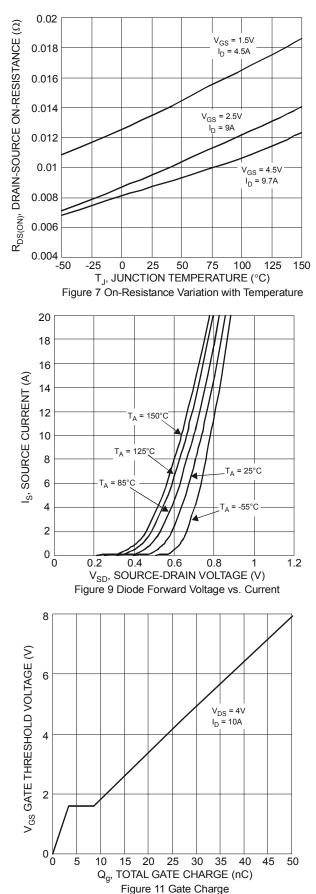


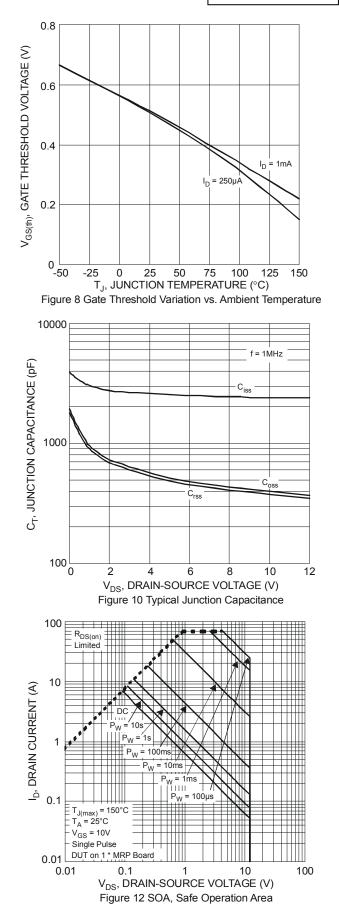
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DMN1019USN Document number: DS36999 Rev. 2 - 2

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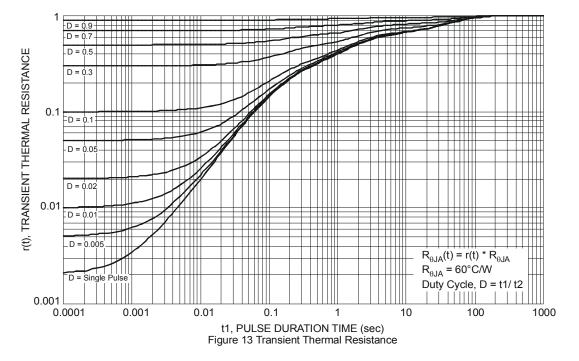






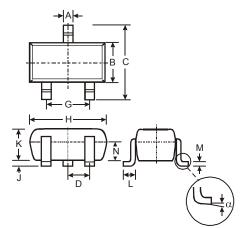
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Package Outline Dimensions

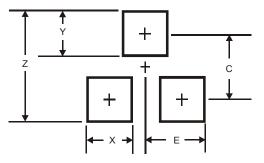
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.



SC59							
Dim	Min	Max	Тур				
Α	0.35	0.50	0.38				
в	1.50	1.70	1.60				
С	2.70	3.00	2.80				
D	-	-	0.95				
G	-	-	1.90				
н	2.90	3.10	3.00				
J	0.013	0.10	0.05				
к	1.00	1.30	1.10				
L	0.35	0.55	0.40				
М	0.10	0.20	0.15				
Ν	0.70	0.80	0.75				
α	0°	8°	-				
All Dimensions in mm							

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
Z	3.4
X	0.8
Y	1.0
С	2.4
E	1.35



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